PCN#:[HPLM-2025-0258]

Product Change Notice (PCN)

Subject: Addition of Cu-wire supplier for RH850/P1 Series LQFP products
Publication Date: 10/1/2025
Effective Date: 4/9/2026
Revision Description: Initial Release
Description of Change:
Renesas will add a Cu-wire supplier for RH850/P1 Series LQFP products as follows:

Item	Before Change	After Change
Addition of Cu-wire supplier	Supplier A	Supplier A and Supplier B

Applicable Assembly Factory
Renesas Semiconductor (Suzhou) Co., Ltd.

Affected Product List: Refer to “Product List” in “Appendix”.

Reason for Change: For stable product supply by adding Cu-wire suppliers.

Impact on Fit, Form, Function, Quality & Reliability:
The change will have no impact on the form, fit, function, quality and reliability of the devices.

Product Identification:
Our production history data can be queried by using the trace code of the product.

Qualification Status: Refer to “Q100 Qualification Test Results” in “Appendix”.

Sample Availability Date: N/A

Device Material Declaration: Available upon request

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the changes as approved.

2. If timely acknowledgement is provided by customers, then customers shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If customers fail to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.

3. If customer cannot accept the PCN then customers must provide Renesas with the last order quantity and purchase order.

For additional information regarding this notice, please contact your Renesas sales representative.

Appendix

Product List

RH850/P1 series :

R7F701336EAFP#KA1	R7F701366EAFP-C#AA1	R7F701310GAFA-C#KA4	R7F701375EAFP-C#BA2
R7F701337EAFP#KA1	R7F701366GAFA-C#AA1	R7F701312EAFP-C#KA1	R7F701376EAFP-C#BA2
R7F701339EAFP#TA1	R7F701319EAFP-C#AA1	R7F701312GAFA-C#KA1	R7F701376GAFA-C#BA2
R7F701341EAFP#TA1	R7F701321EAFP-C#AA1	R7F701314EAFP-C#KA1	R7F701377EAFP-C#BA2
R7F701343EAFP#TA1	R7F701323EAFP-C#AA1	R7F701314GAFA-C#KA1	R7F701378EAFP-C#BA2
R7F701388EAFP-C#HA1	R7F701363EAFP-C#AA1	R7F701311EAFP-C#KA1	R7F701378GAFA-C#BA2
R7F701389EAFP-C#RA1	R7F701363EAFP-C#AAT	R7F701313EAFP-C#KA1	R7F701379EAFP-C#BA2
R7F701390EAFP-C#RA1	R7F701365EAFP-C#AA1	R7F701315EAFP-C#KA1	R7F701380EAFP-C#BA2
R7F701391EAFP-C#RA1	R7F701367EAFP-C#AA1	R7F701318EAFP-C#KA1	R7F701380GAFA-C#BA2
R7F701388EAFP-C#AA1	R7F701304EAFP-C#BA1	R7F701318GAFA-C#KA1	R7F701381EAFP-C#BA2
R7F701389EAFP-C#AA1	R7F701304GAFA-C#BA1	R7F701320EAFP-C#KA1	R7F701382EAFP-C#BA2
R7F701390EAFP-C#AA1	R7F701305EAFP-C#BA1	R7F701320GAFA-C#KA1	R7F701382GAFA-C#BA2
R7F701391EAFP-C#AA1	R7F701310EAFP-C#BA1	R7F701322EAFP-C#KA1	R7F701383EAFP-C#BA2
R7F701388EAFP-C#BA1	R7F701310GAFA-C#BA1	R7F701322GAFA-C#KA1	R7F701384EAFP-C#BA2
R7F701389EAFP-C#BA1	R7F701310EAFP-C#BA4	R7F701362EAFP-C#KA1	R7F701384GAFA-C#BA2
R7F701390EAFP-C#BA1	R7F701310GAFA-C#BA4	R7F701362GAFA-C#KA1	R7F701385EAFP-C#BA2
R7F701391EAFP-C#BA1	R7F701312EAFP-C#BA1	R7F701364EAFP-C#KA1	R7F701386EAFP-C#BA2
R7F701330AEAFP#KA1	R7F701312GAFA-C#BA1	R7F701364GAFA-C#KA1	R7F701386GAFA-C#BA2
R7F701331AEAFP#KA1	R7F701314EAFP-C#BA1	R7F701366EAFP-C#KA1	R7F701375EAFP-C#KA2
R7F701374AEAFP-C#HA1	R7F701314GAFA-C#BA1	R7F701366GAFA-C#KA1	R7F701376EAFP-C#KA2
R7F701374AEAFP-C#AA1	R7F701311EAFP-C#BA1	R7F701319EAFP-C#KA1	R7F701376GAFA-C#KA2
R7F701374AEAFP-C#BA1	R7F701313EAFP-C#BA1	R7F701321EAFP-C#KA1	R7F701377EAFP-C#KA2
R7F701374AEAFP-C#BAT	R7F701315EAFP-C#BA1	R7F701323EAFP-C#KA1	R7F701378EAFP-C#KA2
R7F701374AEAFP-C#BAU	R7F701318EAFP-C#BA1	R7F701363EAFP-C#KA1	R7F701378GAFA-C#KA2
R7F701304EAFP-C#AA1	R7F701318GAFA-C#BA1	R7F701363EAFP-C#KAT	R7F701379EAFP-C#KA2
R7F701304GAFA-C#AA1	R7F701320EAFP-C#BA1	R7F701365EAFP-C#KA1	R7F701380EAFP-C#KA2
R7F701305EAFP-C#AA1	R7F701320GAFA-C#BA1	R7F701367EAFP-C#KA1	R7F701380GAFA-C#KA2
R7F701310EAFP-C#AA1	R7F701322EAFP-C#BA1	R7F701310E***AFP-C#KA4	R7F701381EAFP-C#KA2
R7F701310GAFA-C#AA1	R7F701322GAFA-C#BA1	R7F701318E***AFP-C#KA1	R7F701382EAFP-C#KA2
R7F701310EAFP-C#AA4	R7F701362EAFP-C#BA1	R7F701362E***AFP-C#KA1	R7F701382GAFA-C#KA2
R7F701310GAFA-C#AA4	R7F701362GAFA-C#BA1	R7F701375EAFP-C#AA2	R7F701383EAFP-C#KA2
R7F701312EAFP-C#AA1	R7F701364EAFP-C#BA1	R7F701376EAFP-C#AA2	R7F701384EAFP-C#KA2
R7F701312GAFA-C#AA1	R7F701364GAFA-C#BA1	R7F701376GAFA-C#AA2	R7F701384GAFA-C#KA2
R7F701314EAFP-C#AA1	R7F701366EAFP-C#BA1	R7F701377EAFP-C#AA2	R7F701385EAFP-C#KA2
R7F701314GAFA-C#AA1	R7F701366GAFA-C#BA1	R7F701378EAFP-C#AA2	R7F701386EAFP-C#KA2
R7F701311EAFP-C#AA1	R7F701319EAFP-C#BA1	R7F701378GAFA-C#AA2	R7F701386GAFA-C#KA2
R7F701313EAFP-C#AA1	R7F701321EAFP-C#BA1	R7F701379EAFP-C#AA2	R7F701378E***AFP-C#KA2
R7F701315EAFP-C#AA1	R7F701323EAFP-C#BA1	R7F701380EAFP-C#AA2	
R7F701318EAFP-C#AA1	R7F701363EAFP-C#BA1	R7F701380GAFA-C#AA2	
R7F701318GAFA-C#AA1	R7F701363EAFP-C#BAT	R7F701381EAFP-C#AA2	
R7F701320EAFP-C#AA1	R7F701365EAFP-C#BA1	R7F701382EAFP-C#AA2	
R7F701320GAFA-C#AA1	R7F701367EAFP-C#BA1	R7F701382GAFA-C#AA2	
R7F701322EAFP-C#AA1	R7F701304EAFP-C#KA1	R7F701383EAFP-C#AA2	
R7F701322GAFA-C#AA1	R7F701304GAFA-C#KA1	R7F701384EAFP-C#AA2	
R7F701362EAFP-C#AA1	R7F701305EAFP-C#KA1	R7F701384GAFA-C#AA2	
R7F701362GAFA-C#AA1	R7F701310EAFP-C#KA1	R7F701385EAFP-C#AA2	
R7F701364EAFP-C#AA1	R7F701310GAFA-C#KA1	R7F701386EAFP-C#AA2	
R7F701364GAFA-C#AA1	R7F701310EAFP-C#KA4	R7F701386GAFA-C#AA2	

*** means ROM code

Q100 Qualification Test Results

AEC-Q100-REV-H

[Note : Qualification tests were performed using a representative product with the same wafer process and the same package structure, and also using generic data.]

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
TEST GROUP A – ACCELERATED ENVIRONMENT STRESS TESTS								
PC	A1	JESD22 A113 J-STD-020	Preconditioning: (Test @ Rm) SMD only; Moisture Preconditioning for THB/HAST, AC/UHST, TC, &PTC ; Peak Reflow Temp=260°C	Min.MSL=3			MSL=3	-
THB ~~or~~ ~~HAST~~	A2	JESD22 A101	Temperature Humidity Bias: (Test @ Rm/Hot) Ta=85°C, RH=85%, 1000hrs	3	77	231	0 of 231	-
~~AC or~~ UHST ~~or TH~~	A3	JESD22 A118	Unbiased Highly Accelerated Stree Test: (Test @ Rm) Ta=110°C, 85% RH, 264h	3	77	231	0 of 231	-
TC	A4	JESD22 A104	Temperature Cycle: (Test @ Hot) Ta=-55°C to 150°C, 2000cyc	3	77	231	0 of 231 0 Fails after TC (WBP)	-
PTC	A5	JESD22 A105	Power Temperature Cycle: (Test @ Rm/Hot) -	-	-	-	-	N/A
HTSL	A6	JESD22 A103	High Temperature Storage Life: (Test @ Rm/Hot) Ta=175°C, 1000hrs	1	45	45	0 of 45	-
TEST GROUP B – ACCELERATED LIFETIME SIMULATION TESTS								
HTOL	B1	JESD22 A108	High Temp Operating Life: (Test @ Rm/Cold/Hot) Ta=150°C, 1000hrs	3	77	231	0 of 231	-
ELFR	B2	AEC-Q100-008	Early Life Failure Rate: (Test @ Rm/Hot) Ta=150°C, 48hrs	3	800	2400	0 of 2400	-
EDR	B3	AEC-Q100-005	NVM Endurance & Data Retention Test: (Test @ Rm/Hot) – For HTOL	3	77	231	0 of 231	-
			NVM Endurance & Data Retention Test: (Test @ Rm/Hot) – For HTSL	1	45	45	0 of 45	-
TEST GROUP C – PACKAGE ASSEMBLY INTEGRITY TESTS								
WBS	C1	AEC-Q100-001 AEC-Q003	Wire Bond Shear Test: (Cpk > 1.67)	30 bonds	5 parts Min.	30 bonds	0 of 30bonds	Cpk>1.67
WBP	C2	Mil-STD-883 Method 2011 AEC-Q003	Wire Bond Pull: (Cpk > 1.67); Each bonder used	30 bonds	5 parts Min.	30 bonds	0 of 30bonds	Cpk>1.67
SD	C3	JESD22 B102 JSTD-002D	Solderability: (>95% coverage) 8 hr steam aging prior to testing	1	15	15	0 of 15	-
PD	C4	JESD22 B100, JESD22 B108 AEC-Q003	Physical Dimensions: (Cpk > 1.67)	3	10	30	0 of 30	Cpk>1.67
SBS	C5	AEC-Q100-010 AEC-Q003	Solder Ball Shear: (Cpk > 1.67); 5 balls from min. of 10 devices	3	50balls	150	0 of 150	N/A
LI	C6	JESD22 B105	Lead Integrity: (No lead cracking or breaking); Through-hole only; 10 leads from each of 5 devices	-	-	-	-	N/A
TEST GROUP D – DIE FABRICATION RELIABILITY TESTS								
EM	D1	JESD61	Electromigration:	-	-	-	Pass	Confirmed by process TEG
TDDB	D2	JESD35	Time Dependant Dielectric Breakdown:	-	-	-	Pass	Confirmed by process TEG
HCI	D3	JESD60 & 28	Hot Carrier Injection:	-	-	-	Pass	Confirmed by process TEG
NBTI	D4	JESD90	Negative Bias Temperature Instability:	-	-	-	Pass	Confirmed by process TEG
SM	D5	JESD61,87 & 202	Stress Migration:	-	-	-	Pass	Confirmed by process TEG

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
TEST GROUP E- ELECTRICAL VERIFICATION								
TEST	E1	User/Supplier Specification	Pre and Post Stress Electrical Test:	All	All	All	0 of All	-
HBM	E2	AEC-Q100-002	Electrostatic Discharge, Human Body Model: (Test @ Rm/Hot); (2KV HBM / Class 2 or better)	1	3	3	0 of 3 ESD Level= HBM:2	HBM>2KV
CDM	E3	AEC-Q100-011	Electrostatic Discharge, Charged Device Model: (Test @ Rm/Hot); (750V corner leads, 500V all other leads / Class C4B or better)	1	3	3	0 of 3 ESD Level= CDM:C4B	Corner leads: 750V Pass All other leads:500V Pass
LU	E4	AEC-Q100-004	Latch-Up: (Test @ Rm/Hot)	1	6	6	0 of 6	-
ED	E5	AEC-Q100-009 AEC-Q003	Electrical Distributions: (Test @ Rm/Hot/Cold) (where applicable, Cpk>1.67)	3	30	90	Cpk>1.67	-
FG	E6	AEC-Q100-007	Fault Grading:	-	-	-	>98%	-
CHAR	E7	AEC-Q003	Characterization: (Test @ Rm/Hot/Cold)	-	-	-	Pass	According to Renesas standard procedure
EMC	E9	SAE J1752/3	Electromagnetic Compatibility (Radiated Emissions)	1	1	1	0 of 1	-
SC	E10	AEC Q100-012	Short Circuit Characterization	-	-	-	-	N/A
SER	E11	JESD89-1 JESD89-2 JESD89-3	Soft Error Rate	1	3	3	Pass	-
LF	E12	AEC-Q005	Lead (Pb) Free: (see AEC-Q005)	-	-	-	Pass	Solderability: See SD (C3) result. Solder heat resistance: N/A (Wave Solder is Not recommended.) Whisker: Performed on product TEG with test method based on JESD201.
TEST GROUP F – DEFECT SCREENING TESTS								
PAT	F1	AEC-Q001	Process Average Testing: (see AEC-Q001)	All	All	All	Reject units outside PAT limits	Apply to mass production according to Renesas standard procedure
SBA	F2	AEC-Q002	Statistical Bin/Yield Analysis: (see AEC-Q002)	All	All	All	Reject units outside criteria	Apply to mass production according to Renesas standard procedure
TEST GROUP G – CAVITY PACKAGE INTEGRITY TESTS (for Ceramic Package testing only)								
MS	G1	JESD22 B104	Mechanical Shock: (Test @ Rm)	-	-	-	-	N/A
VFV	G2	JESD22 B103	Variable Frequency Vibration: (Test @ Rm)	-	-	-	-	N/A
CA	G3	MIL-STD-883 Method 2001	Constant Acceleration: (Test @ Rm)	-	-	-	-	N/A
GFL	G4	MIL-STD-883 Method 1014	Gross and Fine Leak:	-	-	-	-	N/A
DROP	G5	----------	Drop Test: (Test @ Rm) MEMS cavity parts only. Drop part on each of 6 axes once from a height of 1.2m onto a concrete surface.	-	-	-	-	N/A
LT	G6	MIL-STD-883 Method 2004	Lid Torque:	-	-	-	-	N/A
DS	G7	MIL-STD-883 Method 2019	Die Shear:	-	-	-	-	N/A
IWV	G8	MIL-STD-883 Method 1018	Internal Water Vapor:	-	-	-	-	N/A